



Material Content Data Sheet



Sales Product Name		BSP298 H6327		Issued		27. September 2017		
MA#		MA001096130						
Package		PG-SOT223-4-21		Weight*		114.26 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.807	2.46	2.46	24563	24563
leadframe	inorganic material	silicon	7440-21-3	0.010	0.01		89	
	non noble metal	titanium	7440-32-6	0.051	0.04		444	
	non noble metal	chromium	7440-47-3	0.152	0.13		1331	
wire	non noble metal	copper	7440-50-8	50.489	44.19	44.37	441886	443750
	non noble metal	copper	7440-50-8	0.015	0.01	0.01	129	129
	encapsulation	organic material	carbon black	1333-86-4	0.579	0.51		5066
encapsulation	plastics	epoxy resin	-	8.683	7.60		75997	
	inorganic material	silicondioxide	60676-86-0	48.626	42.56	50.67	425582	506645
leadfinish	non noble metal	tin	7440-31-5	1.464	1.28	1.28	12813	12813
plating	noble metal	silver	7440-22-4	0.513	0.45	0.45	4490	4490
glue	plastics	epoxy resin	-	0.152	0.13		1332	
	noble metal	silver	7440-22-4	0.717	0.63	0.76	6278	7610
*deviation	< 10%					Sum in total:	100.00	1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
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3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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